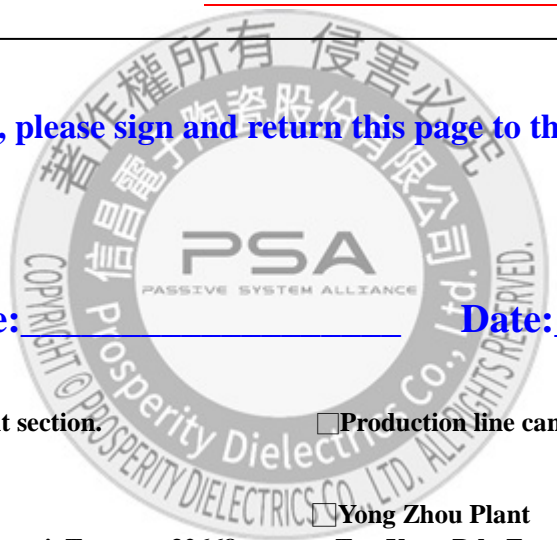




SPECIFICATION FOR APPROVAL

CUSTOMER	_____
CUST. PART NO.	_____
CUST. DOC. REV.	_____
DESCRIPTION	POWER CHOKE(RoHS+H.F.)
SAMPLE LOT NO.	_____
PART NO.	CSMH2412D-XXXX-LRH
DOC. REV.	_____
DATE	_____

Once you approve this part, please sign and return this page to the following marked location.



Customer Signature: _____ Date: _____

- This part currently development section. Production line can produce this series of products.

■ Sales Office-Headquarter

No. 566-1, Kao-Shi Rd., Yangmei, Taoyuan 32668,
Taiwan
TEL: +886-3-475-3355
FAX: +886-3-485-4959

□ Yong Zhou Plant

Tao-Yuan Rd., Fenghuang Park, Lengshuitan
District, Yongzhou, Hunan 425000, P.R.C.
TEL: +86-746-8610-180
FAX: +86-746-8610-181

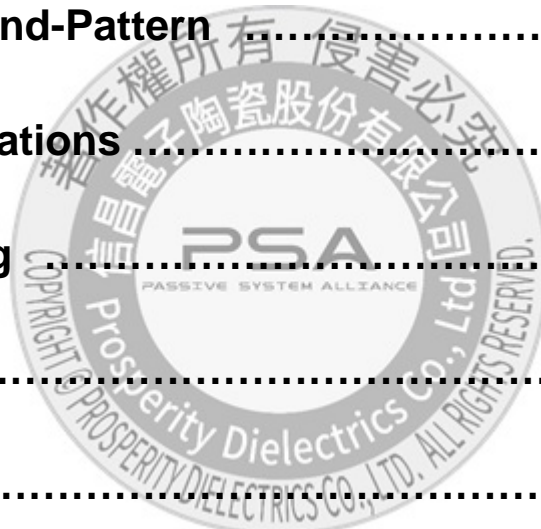
□ Sales Office-Dong Guan,China

No.638,Mei Jing West Road Xiniupo Administrative
Zone Dalang Town,Dong Guan City,GuangDong
Province,China.
TEL: +86-769-8555-0979
FAX: +86-769-8555-0972

TESTED BY	CHECKED BY	APPROVED BY

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SPECIFICATION FOR APPROVAL

CUSTOMER	CUSTOMER P/N	REV. —	SPL. LOT NO.	
PART NAME POWER CHOKE (ROHS+H.F.)	PART NO. CSMH2412D-XXXX-LRH	REV.	DATE OF ISSUE	Q'TY 0 PCS

ENGINEERING CHANGE NOTICE - RECORD

REVISION NO.	REVISION DESCRIPTION	AUTHOR	DATE	REMARK
				

SPECIFICATION FOR APPROVAL

※This is a RoHS and REACH compliant product whose related documents are available on request.
 ※Graphic is only for dimensionally application.

1. Range of application:

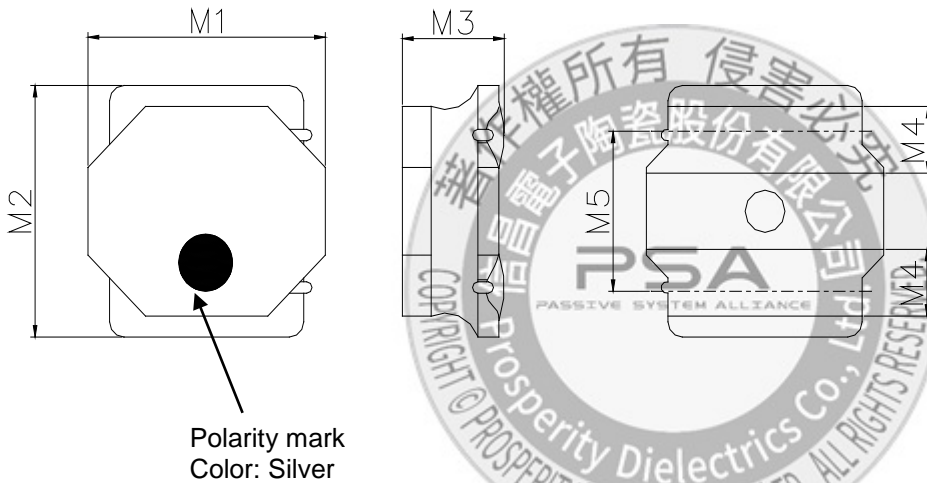
This specifications are applied to SMD Power Inductor, CSMH2412D.

2. Ordering code:

Example: **CSMH** **2412** **D** - **2R2** **M** - □□□ □
 (1) (2) (3) (4) (5) (6) (7)

- (1) Product Type
- (2) External dimensions
- (3) Solder Type
- (4) Inductance
- (5) Inductance tolerance
- (6) Green product code
- (7) Internal Code

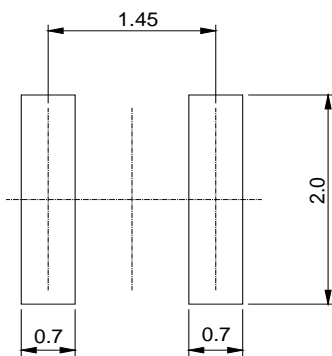
3. Mechanical Dimension:



UNIT : mm

	DIM.	TOL.
M1	2.4	±0.1
M2	2.4	±0.1
M3	1.2	MAX.
M4	0.6	±0.2
M5	1.45	±0.2

4. Recommended Land-Pattern:



(Unit: mm)

Caution

Excessive solder has a risk of occurrence of mounting failure like slant in consequence of reflow condition. In this case, please adjust solder quantity by design Change of stencil size and/or its thickness, etc.

Stencil thickness	※Stencil area
0.10mm	70%
0.12mm	60%
0.15mm	50%

*The above values are shown as scale ratio from our recommended land pattern

SPECIFICATION FOR APPROVAL

5. Electrical Characteristics:

Part number	Nominal Inductance (uH) @100KHz	Inductance Tolerance	DC Resistance (Ω) $\pm 20\%$	Rated Current (mA)		Self-resonant Frequency Min (MHz)
				Saturation Current Idc1	Temperature Rise Current Idc2	
CSMH2412D-R47N-LRH	0.47	$\pm 30\%$	0.050	2900	2100	180
CSMH2412D-1R0N-LRH	1.0	$\pm 30\%$	0.077	2350	1300	101
CSMH2412D-1R5N-LRH	1.5	$\pm 30\%$	0.100	2100	1150	89
CSMH2412D-2R2M-LRH	2.2	$\pm 20\%$	0.140	1700	1000	72
CSMH2412D-3R3M-LRH	3.3	$\pm 20\%$	0.225	1400	750	56
CSMH2412D-4R7M-LRH	4.7	$\pm 20\%$	0.300	1150	650	45
CSMH2412D-6R8M-LRH	6.8	$\pm 20\%$	0.420	950	550	34
CSMH2412D-100M-LRH	10	$\pm 20\%$	0.600	810	450	29

1. Test Frequency: 100KHz

2. Test Equipment:

Inductance: Chroma3302+1320+16502. or equivalent.

DCR: Chroma16502 or equivalent.

SRF: HP4291B or equivalent.

3. Saturation Current Idc1: The value of current causes a 30% inductance reduction from initial value.

4. Temperature rise current Idc2: The value of current causes a 40°C temperature rise.

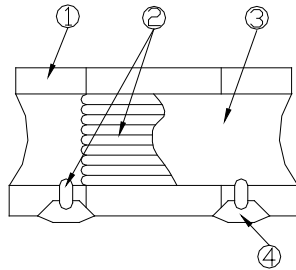
5. Rated Current: Either Idc1 or Idc2 whichever is smaller.

6. Operating Temperature Range: -25°C to +120°C (Including self-temperature rise)

7. Storage Temp. Range : -40°C to +85°C.

8. MSL : Level 1.

6. Structural Drawing :



(Magnetic Shielded Type)

① Ferrite core

Ni-Zn ferrite

② Winding wire

Polyurethane-copper wire

③ Over-coating resin

Epoxy resin, containing ferrite powder

④ Electrode

External electrode (substrate)

Cu

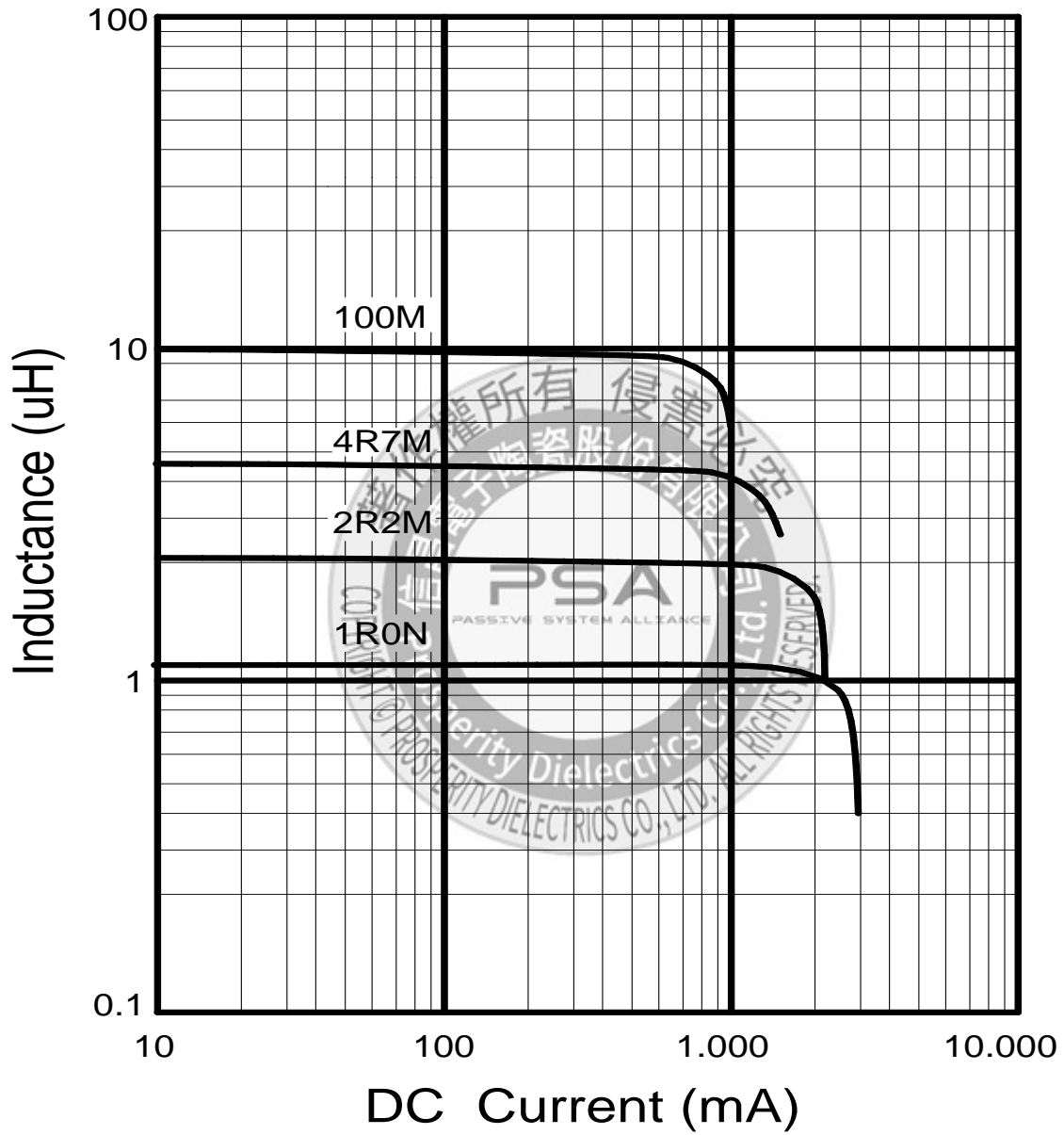
External electrode (top surface solder coating)

Sn-Ag-Cu

SPECIFICATION FOR APPROVAL

7. Electrical Curve :

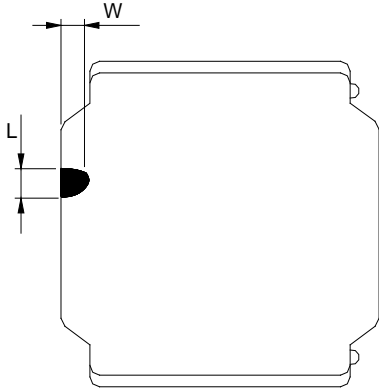
Inductance vs. DC Current



SPECIFICATION FOR APPROVAL

8. Core Chipping:

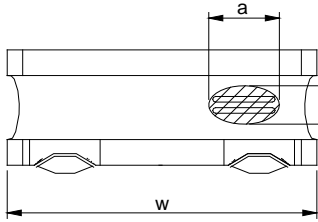
The appearance standard of the chipping size in top side, of bottom side ferrite Core is following dimension



L	W
0.5mmMax.	0.5mmMax.

9. Exposed wire tolerance limit of coating resin part on product side

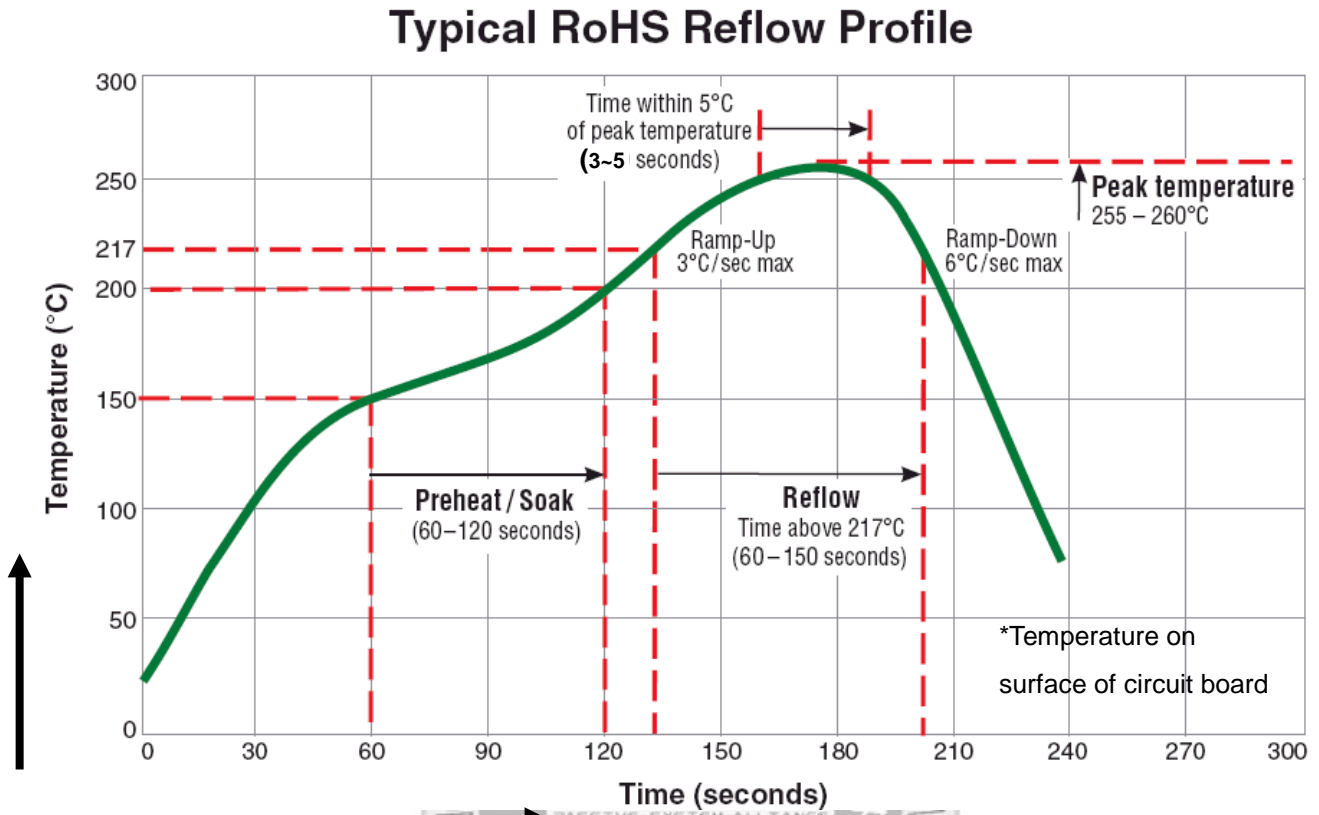
Size of exposed wire occurring to coating resin is specified below.



- ① Width direction (dimension a): Acceptable when $a \leq w/2$
Nonconforming when $a > w/2$
- ② Length direction (dimension b): Dimension b is not specified.
- ③ When total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

SPECIFICATION FOR APPROVAL

10. Reflow Profile Chart (Reference):

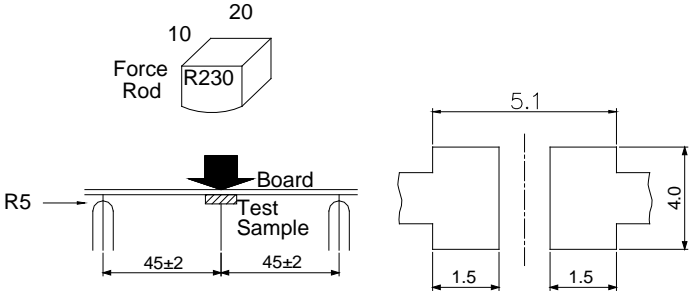
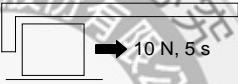
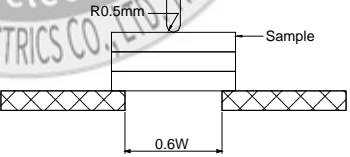


(Table 1)

The products may be exposed to reflow soldering process of above profile up to two times.

SPECIFICATION FOR APPROVAL

11. Mechanical Performance /Environmental Test Performance Specifications:

	Test Item	Standard	Test method
MECHANICAL CHARACTERISTICS	Resistance to Deflection	No damage.	<p>The test samples shall be soldered to the test board by the reflow soldering conditions show in Table 1. As illustrated below, apply force in the direction of the Arrow indicating until deflection of the test board Reaches to 2 mm.</p>  <p style="text-align: right;">Land dimensions</p> <p>Test board size :100×40×10 Test board material I: glass epoxy-resin Solder cream thickness:0.1</p> <p style="text-align: right;">Unit: mm</p>
	Adhesion of Terminal Electrode	Shall not come off PC board	<p>The test samples shall be soldered to the test board By the reflow soldering conditions shown in Table 1.</p>  <p>Applied force:10 N to X and Y directions Duration:5 s. Solder cream thickness:0.1 mm (Refer to recommended Land Pattern Dimensions Defined in "Precaution")</p>
	Body strength	No damage	<p>Applied force :20 N Duration :10 s</p> 

SPECIFICATION FOR APPROVAL

Test Item	Standard	Test method															
Resistance to Vibration	Δ L/L:within \pm 10% No abnormality observed In appearance	The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1.Then It shall be submitted to below test conditions <table border="1" style="width: 100%; margin-top: 5px;"> <tr> <td>Frequency range</td> <td>10Hz~55Hz</td> </tr> <tr> <td>Total Amplitude</td> <td>1.5mm(May not exceed acceleration 196 m/S²)</td> </tr> <tr> <td>Sweeping Method</td> <td>10Hz to 55Hz to 10 Hz for 1 min.</td> </tr> <tr> <td>Time</td> <td>For 2 hours on each X,Y, and Z axis.</td> </tr> </table>	Frequency range	10Hz~55Hz	Total Amplitude	1.5mm(May not exceed acceleration 196 m/S ²)	Sweeping Method	10Hz to 55Hz to 10 Hz for 1 min.	Time	For 2 hours on each X,Y, and Z axis.							
Frequency range	10Hz~55Hz																
Total Amplitude	1.5mm(May not exceed acceleration 196 m/S ²)																
Sweeping Method	10Hz to 55Hz to 10 Hz for 1 min.																
Time	For 2 hours on each X,Y, and Z axis.																
Resistance to Soldering heat (Reflow)	Δ L/L:within \pm 10% No abnormality observed In appearance	The test sample shall be exposed to reflow oven at 230 \pm 5 deg C for 40 seconds, with peak temperature at 260 \pm 5 deg C for 5 seconds, 2 times. Test board thickness:1.0 mm Test board material :glass epoxy-resin															
Solder ability	At least 90% of surface of terminal electrode is covered by new solder.	The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25% <table border="1" style="width: 100%; margin-top: 5px;"> <tr> <td>Solder Temperature</td> <td>245\pmdeg C</td> </tr> <tr> <td>Time</td> <td>5\pm1.0 S.</td> </tr> <tr> <td>Immersing Speed</td> <td>25 mm/s</td> </tr> </table>	Solder Temperature	245 \pm deg C	Time	5 \pm 1.0 S.	Immersing Speed	25 mm/s									
Solder Temperature	245 \pm deg C																
Time	5 \pm 1.0 S.																
Immersing Speed	25 mm/s																
Temperature Characteristics	Δ L/L:within \pm 20% No abnormality observed In appearance	Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated.															
Thermal shock	Δ L/L:within \pm 10% No abnormality observed In appearance	The test samples shall be soldered to test board By the reflow soldering conditions shown in Table 1. The test samples shall be placed at specified Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle <table border="1" style="width: 100%; margin-top: 5px;"> <thead> <tr> <th>Step</th> <th>Temperature</th> <th>Time(min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40\pm3 deg C</td> <td>30\pm3</td> </tr> <tr> <td>2</td> <td>Room Temp</td> <td>3 maximum</td> </tr> <tr> <td>3</td> <td>85\pm2 deg C</td> <td>30\pm3</td> </tr> <tr> <td>4</td> <td>Room Temp</td> <td>3 maximum</td> </tr> </tbody> </table>	Step	Temperature	Time(min)	1	-40 \pm 3 deg C	30 \pm 3	2	Room Temp	3 maximum	3	85 \pm 2 deg C	30 \pm 3	4	Room Temp	3 maximum
Step	Temperature	Time(min)															
1	-40 \pm 3 deg C	30 \pm 3															
2	Room Temp	3 maximum															
3	85 \pm 2 deg C	30 \pm 3															
4	Room Temp	3 maximum															
Low Temperature life Test	Δ L/L:within \pm 10% No abnormality observed In appearance	The test samples shall be soldered to the test board by The reflow soldering conditions shown in Table 1. After that, the test samples shall be placed at test Conditions as shown in below table. <table border="1" style="width: 100%; margin-top: 5px;"> <tr> <td>Temperature</td> <td>-40\pm2 deg C</td> </tr> <tr> <td>Time</td> <td>500 +24/-0 h</td> </tr> </table>	Temperature	-40 \pm 2 deg C	Time	500 +24/-0 h											
Temperature	-40 \pm 2 deg C																
Time	500 +24/-0 h																

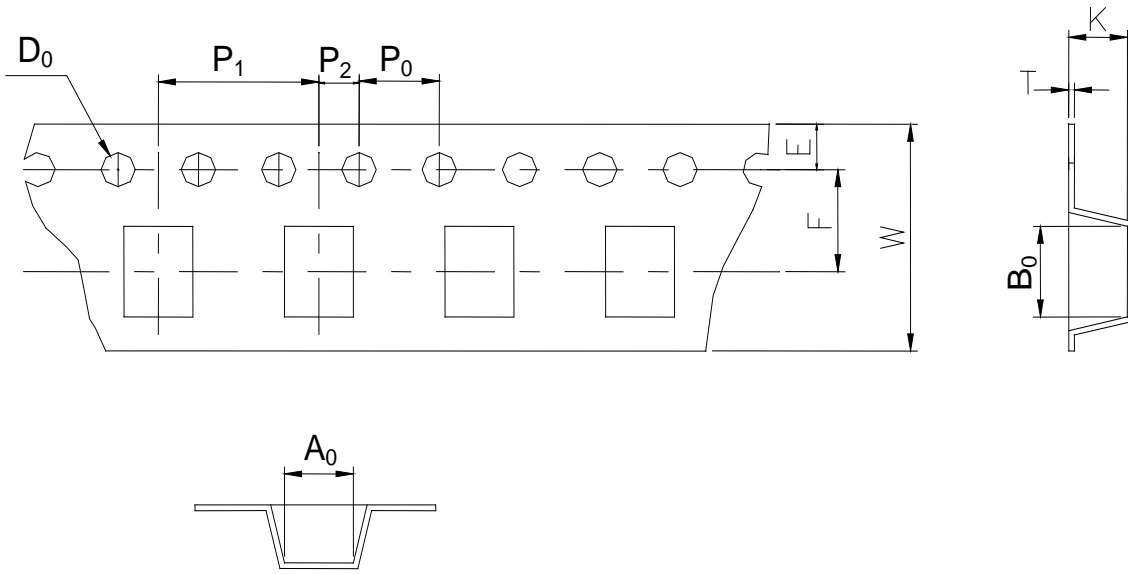
SPECIFICATION FOR APPROVAL

	Test Item	Standard	Test method							
ENVIRONMENT TESTS	Loading at high temperature life test	$\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 1. The test samples shall be placed in thermostatic oven set at specified temperature and applied the rated current continuously as shown in below table. <table border="1" style="margin: 10px auto; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperature</td> <td style="text-align: center;">85\pm2 deg C</td> </tr> <tr> <td style="text-align: center;">Applied current</td> <td style="text-align: center;">Rated current (Refer to Page 2)</td> </tr> <tr> <td style="text-align: center;">Time</td> <td style="text-align: center;">500+24/-0 h</td> </tr> </table>	Temperature	85 \pm 2 deg C	Applied current	Rated current (Refer to Page 2)	Time	500+24/-0 h	
	Temperature	85 \pm 2 deg C								
	Applied current	Rated current (Refer to Page 2)								
Time	500+24/-0 h									
Damp heat life test	$\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 1. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table. <table border="1" style="margin: 10px auto; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperature</td> <td style="text-align: center;">60\pm2 deg C</td> </tr> <tr> <td style="text-align: center;">Humidity</td> <td style="text-align: center;">90~95%RH</td> </tr> <tr> <td style="text-align: center;">Time</td> <td style="text-align: center;">500+24/-0 h</td> </tr> </table>	Temperature	60 \pm 2 deg C	Humidity	90~95%RH	Time	500+24/-0 h		
Temperature	60 \pm 2 deg C									
Humidity	90~95%RH									
Time	500+24/-0 h									
Loading under Damp heat life test	$\Delta L/L$: within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Table 1. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table. <table border="1" style="margin: 10px auto; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperature</td> <td style="text-align: center;">60\pm2 deg C</td> </tr> <tr> <td style="text-align: center;">Humidity</td> <td style="text-align: center;">90~95%RH</td> </tr> <tr> <td style="text-align: center;">Applied current</td> <td style="text-align: center;">Rated current (Refer to Page 2))</td> </tr> <tr> <td style="text-align: center;">Time</td> <td style="text-align: center;">500+24/-0 h</td> </tr> </table>	Temperature	60 \pm 2 deg C	Humidity	90~95%RH	Applied current	Rated current (Refer to Page 2))	Time	500+24/-0 h
Temperature	60 \pm 2 deg C									
Humidity	90~95%RH									
Applied current	Rated current (Refer to Page 2))									
Time	500+24/-0 h									

SPECIFICATION FOR APPROVAL

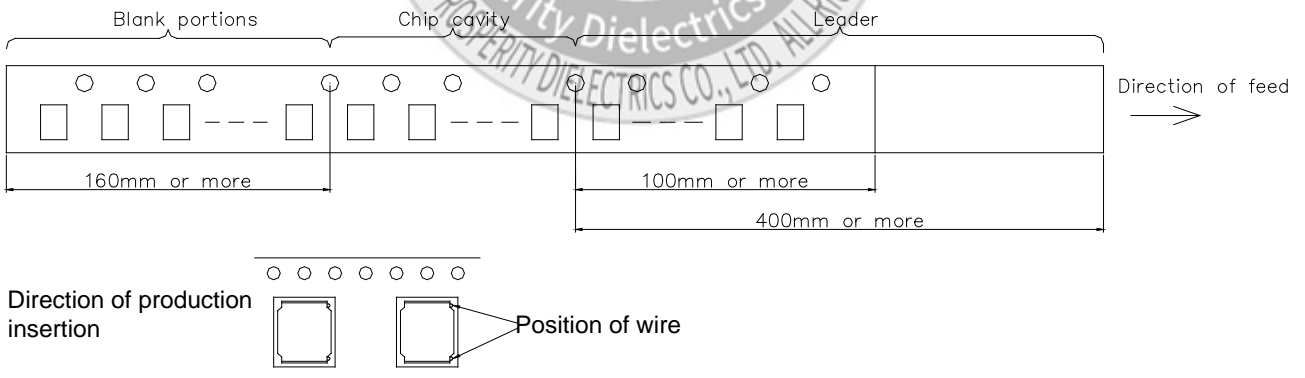
12. Tape & Reel Packaging Dimensions: 12-1 Dimensions

Unit: mm



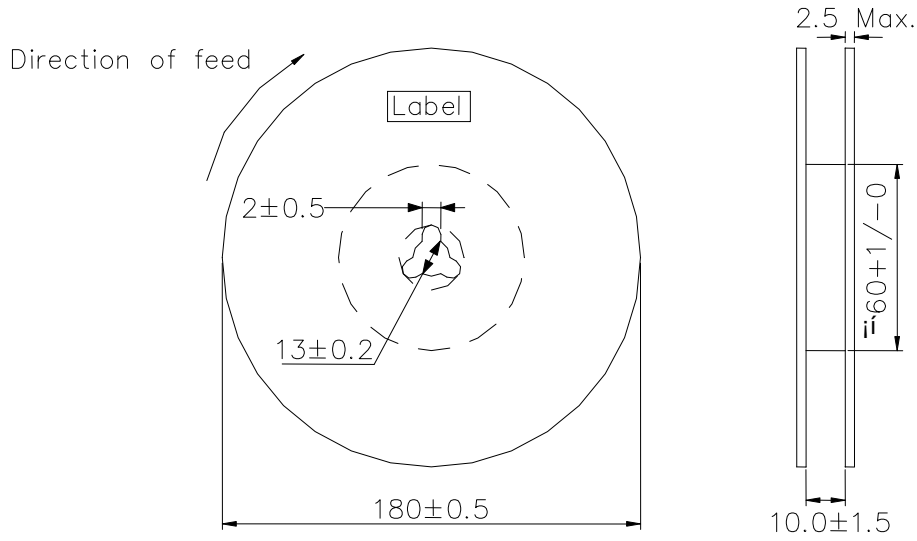
A_0	B_0	W	F	E	P_1	P_2	P_0	D_0	T	K
2.6 ± 0.1	2.6 ± 0.1	8.0 ± 0.2	3.5 ± 0.1	1.75 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	4.0 ± 0.1	$\Phi 1.5$ $+0.1$ -0	0.25 ± 0.05	1.3 ± 0.1

12-2 Direction of rolling



SPECIFICATION FOR APPROVAL

12-3 Reel



Label position: on the opposite side of sprocket holes side of reel

12-4 Top tape strength



Peel-off strength: 0.1N~0.7N

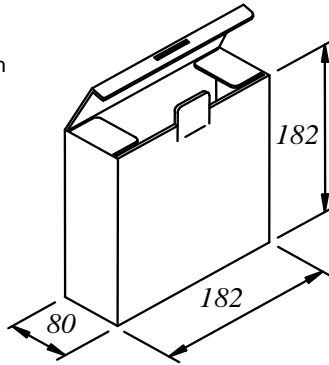
Peel-off angle: $165^\circ \sim 180^\circ$

Peel-off speed: 300mm/mm

SPECIFICATION FOR APPROVAL

12-5 Dimensions of packing box (for Tape & Reel package)

UNIT : mm



CONSTRUCTION:

THE CASE CONTAINS 5-8mm WIDE CARRIER TAPES.

Q'TY : 2,500/ REEL



TOTAL Q'TY : 75,000 PCS